Part

目录

电性参数

[redacted]

可靠性实验

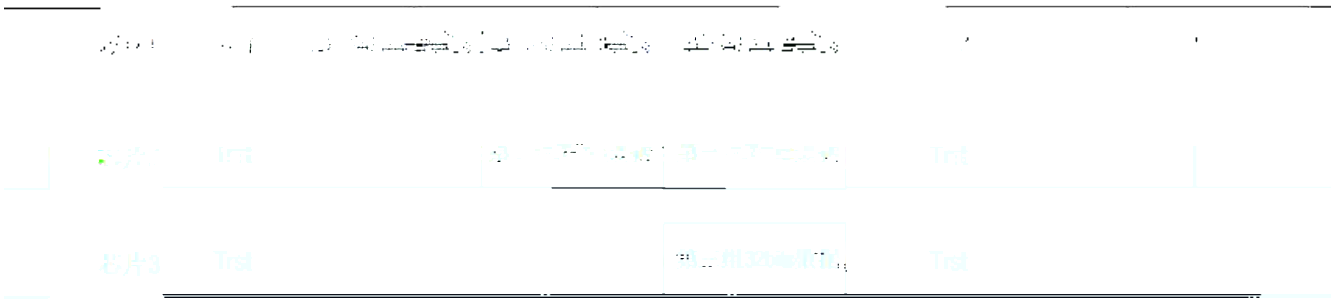
[redacted]

包装

[redacted]

[redacted]

Part



1 MCU 2 3

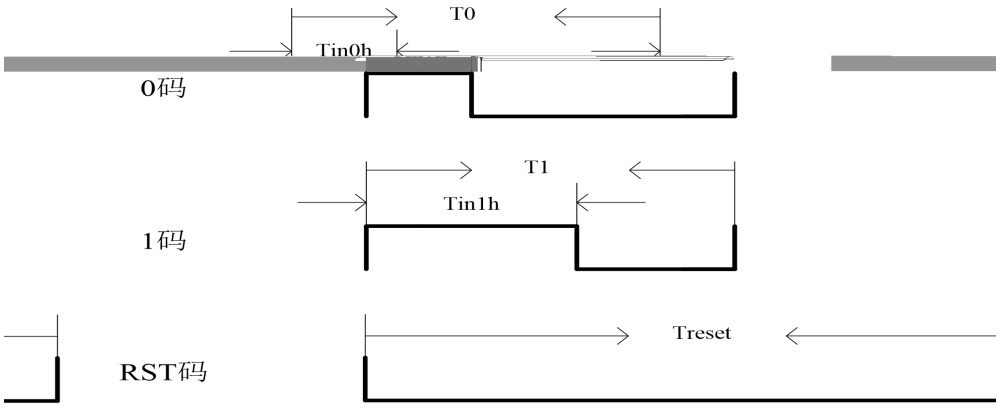
Note: D1 refers to the data sent by MCU, and D2, D3 and D4 refer to the data automatically shaped and forwarded by cascade circuit

32bit

GRBW

Note: high order first send, send data in the order of GrB

:



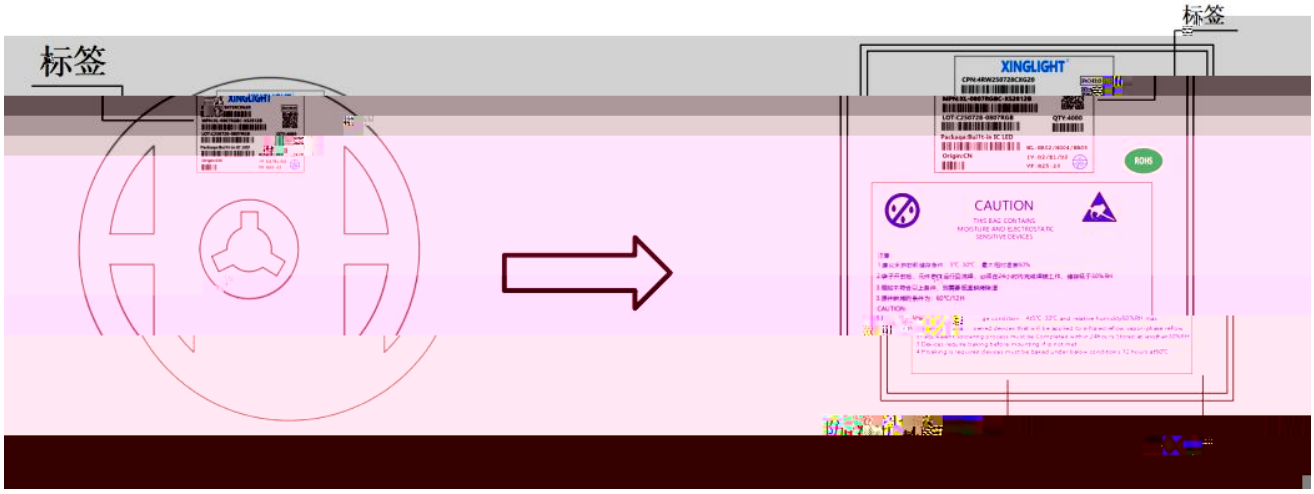
Part

Part

包装（2）

Packaging (2)

◇ 防潮抗静电包装 Moisture Proof and Antti-Electrostic Foil Bag



◇ 外箱包装 Cardboard Box

◇ 标签说明 Label Explanation

焊接指导（1）

Guideline for Solder[redacted]

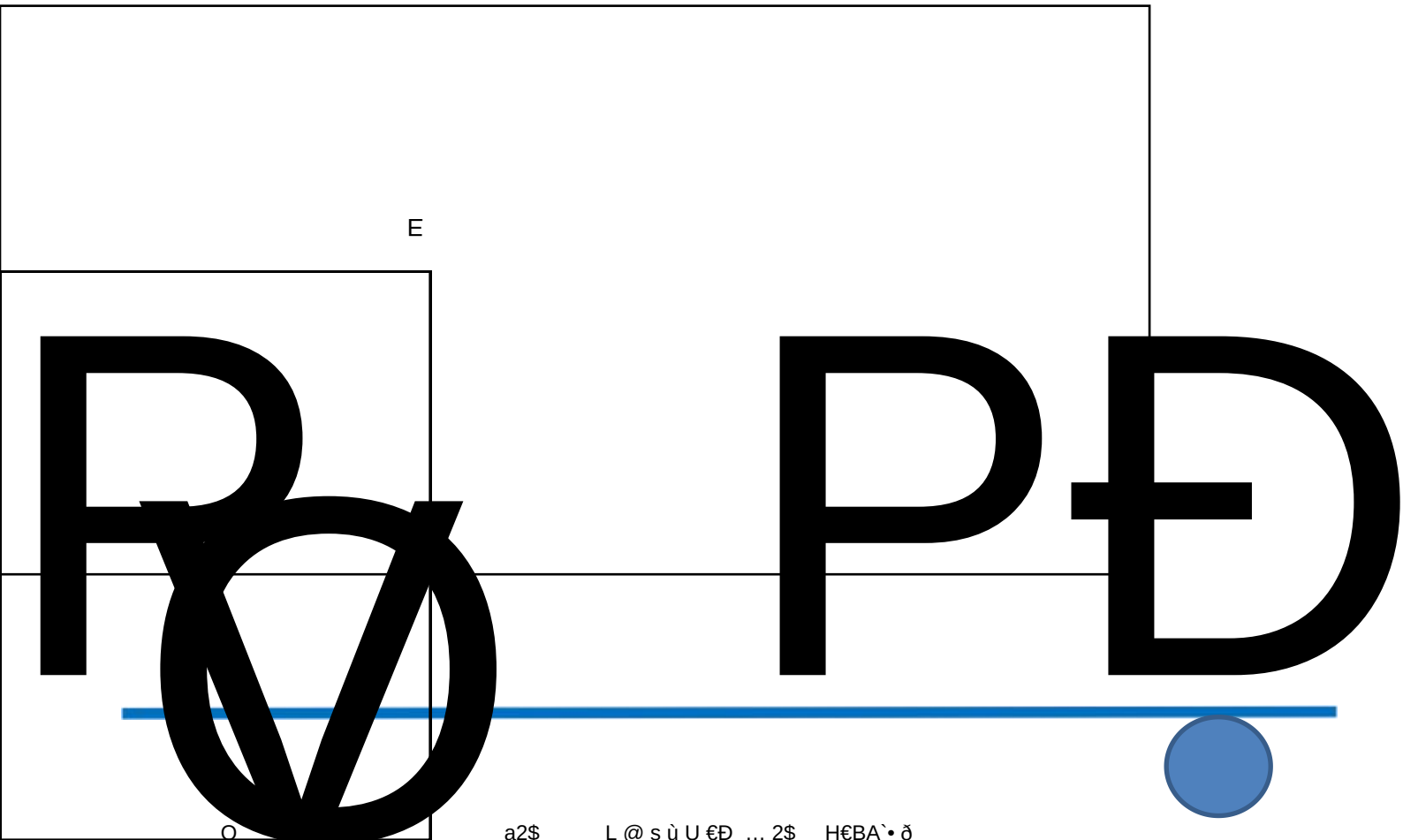
使用烙铁人[redacted]

30

Z Pa °Wb ð a V] 7a G O MQ a F•Ð P

V5 F•BP•a2&A•p

E



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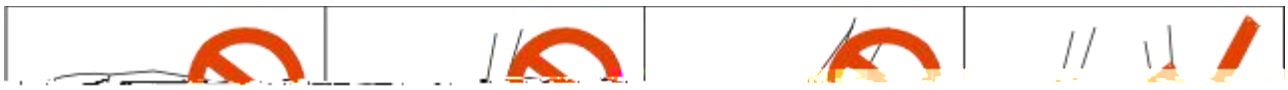
Part

使用注意事项（3）

Precautions (3)

其他事项：



眼睛保护忠告：